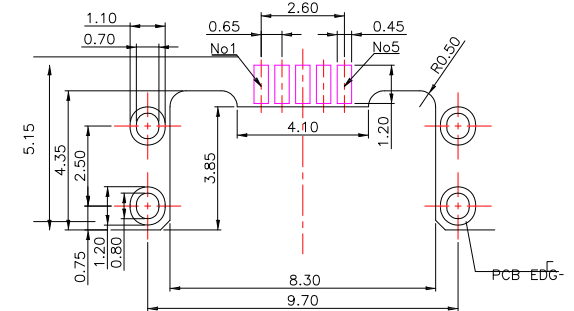
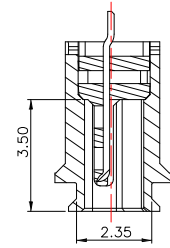
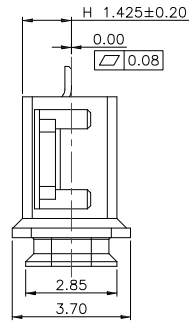
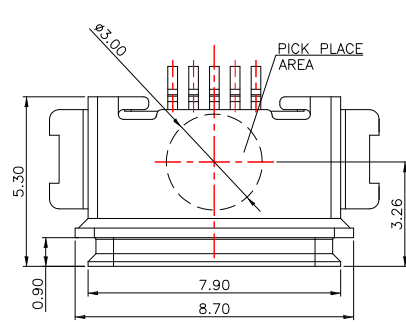
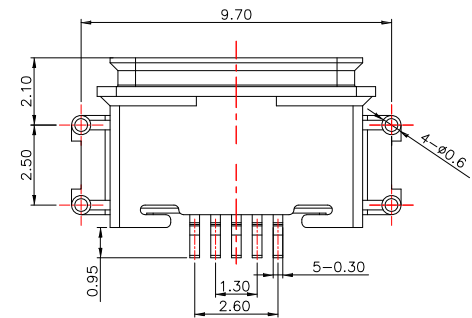
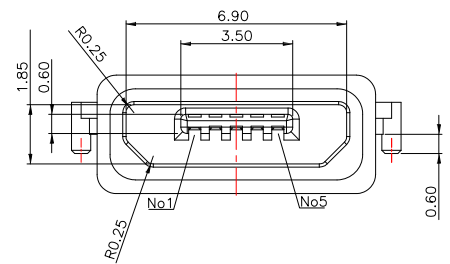


IPX7



P.C.B LAYOUT MOUNTING PATTERN



MRUSB-5B-WP11-x-S382

鍍層厚度 :

Blank : 1u"
2 : 15u"
3 : 30u"

NOTES:

MATERIAL:

- 1.1 HOUSING: HIGH-TEMP
- 1.2 CONTACT: COPPER ALLOY
- 1.3 SHELL: SUS

FINISH:

- 2.1 CONTACT: PLATED GOLD IN MATING AREA ;
GOLD PLATED ON SOLDER BALLS ;
NICKEL UNDER PLATED OVERALL
- 2.2 SHELL: NICKEL UNDER PLATED SURFACE LAYER
- 3.SPECIFICATION:
 - 3.1 RATING: 1.8A(PIN1&5) , 0.5A(PIN2&3&4)
 - 3.2 DIELECTRIC WITHSSTANDING VOLTAGE: 100 VAC
 - 3.3 CONTACT RESISTANCE: 30 mΩ MAX.
 - 3.4 INSULATION RESISTANCE: 1000 MΩ MIN.

CONTACT 建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

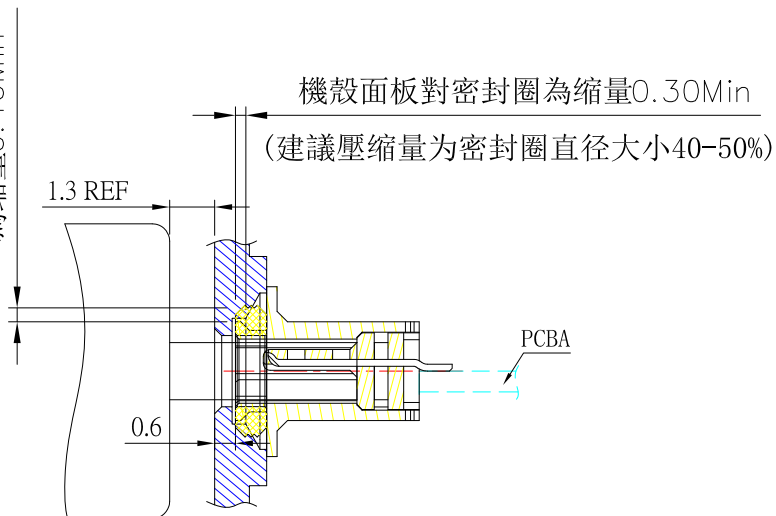
TOLERANCE UNLESS OTHERWISE STATED :	Up to 5 ±0.2	3RD. ANGEL'S	UNITS	MM
	Above 5 ~ 15 ±0.3			
	Above 15 ~ 30 ±0.4			
	Above 30 ~ 50 ±0.5			
	Angle ±0.3°			

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	04/22/20			
CHECKED BY:	DATE	FINISH	MODLE	MICRO USB 5P B TYPE 沉板 板上
Jacky Chen	04/22/20			H 1.42 IPX7
APPROVED BY:	DATE	SCALE	DWG NO.	MRUSB-5B-WP11-x-S382
Tony Kao	04/22/20	1 : 1		
		SHEET NO.	PART NO.	MRUSB-5B-WP11-x-S382
		1 of 2		

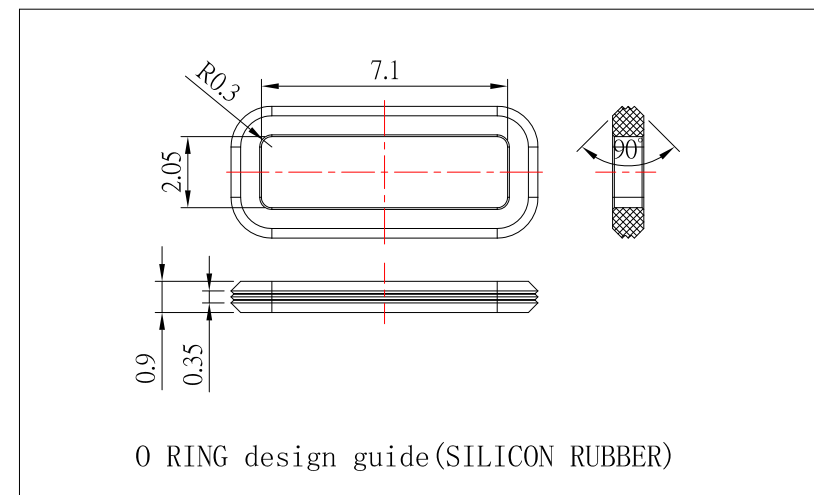
IPX7



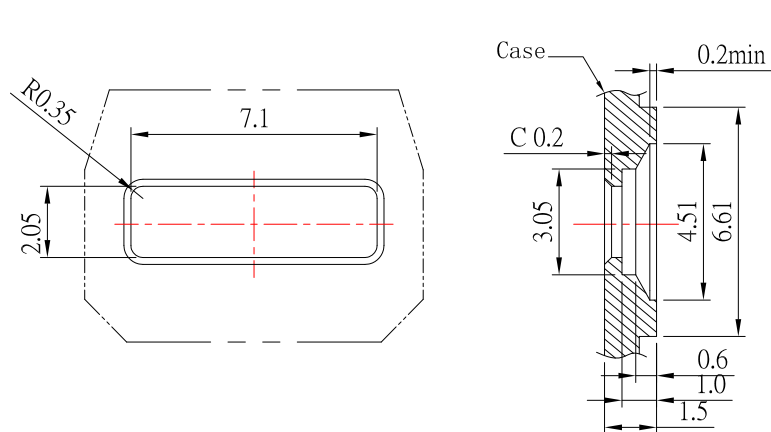
機殼面板對密封圈
為縮量0.40Min



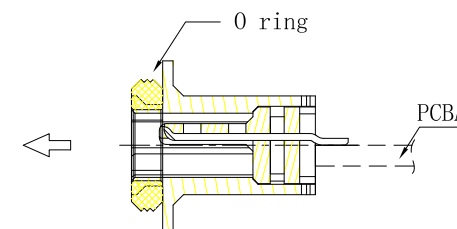
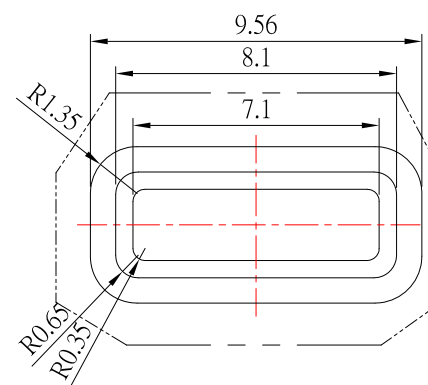
COMPRESSION RATIO TO BE 40%-50%



O RING design guide (SILICON RUBBER)



RECOMMENDED OPEN DIMENSION OF CASE



Assembly direction



建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS
OTHERWISE STATED:

Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3°

3RD.
ANGEL'S



UNITS

MM

DRAWN BY: Jack Lu
CHECKED BY: Jacky Chen
APPROVED BY: Tony Kao

DATE: 04/22/20
DATE: 04/22/20
DATE: 04/22/20

MATL
FINISH
SCALE
SHEET NO.

TITLE
MODLE
DWG NO.
PART NO.

CONNECTOR
MICRO USB 5PF B TYPE 沉板 板上
H 1.42 IPX7
MRUSB-5B-WP11-x-S382
MRUSB-5B-WP11-x-S382

SIZE
A4
VER
R4